



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSO201SP H	Issued	12. August 2021
MA#	MA005617632		
Package	PG-DSO-8-39	Weight*	84.24 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.914	4.65	4.65	46468	46468
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		486	
	non noble metal	iron	7439-89-6	0.820	0.97		9728	
	non noble metal	copper	7440-50-8	33.276	39.50	40.53	395015	405351
wire	non noble metal	copper	7440-50-8	0.236	0.28	0.28	2806	2806
encapsulation	organic material	carbon black	1333-86-4	0.220	0.26		2613	
	plastics	epoxy resin	-	6.825	8.10		81015	
	inorganic material	silicondioxide	60676-86-0	36.985	43.91	52.27	439047	522675
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9661	9661
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	862	862
glue	plastics	epoxy resin	-	0.154	0.18		1827	
	noble metal	silver	7440-22-4	0.872	1.03	1.21	10350	12177
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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